




PCN Number:	20130628003		PCN Date:	07/02/2013	
Title:	Assembly/Test Offload for the LM3401MM* Product Family at AP1 and ASESH				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services
Proposed 1st Ship Date:	10/02/2013	Estimated Sample Availability:	07/03/2013		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
PCN Details					
Description of Change:					
Qualification of the LM3401MM* family of products (8L - VSSOP) in both Amkor Philippines (AP1) and ASE Shanghai (ASEH) for Assembly and test. Material comparison as follows:					
	Carsem	AP1	ASESH		
Mold Compound	8096692	101325958	EN2000515		
Mount Compound	8096585	101374994	EY1000063		
Bond Wire	1.0 Mil Dia., Au	1.0mil Diameter, Au	1.0mil Diameter, Au		
Leadframe (Finish, Base)	Matte Sn, Cu	Matte Sn, Cu	NiPdAu, Cu		
Due to higher demand than forecast at the time of offload, we have exhausted all supply from the prior assembly site (Carsem) and must now ship material from the newly qualified assembly sites (Amkor, AP1 & ASE, ASESH). ** For any desired shipments prior to 90 days from the date of this notification, please notify your TI PCN contact immediately of your approval for this PCN. **					
Reason for Change:					
The LM3401MM* family of products is no longer being assembled and tested out of the original Assy/Test site (Carsem).					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Sample Product Shipping Label (not actual product label)					
Assembly Site					
Carsem (CRS)	Assembly Site Origin (22L)	ASO: CRS			
Amkor/Philippines (AP1)	Assembly Site Origin (22L)	ASO: AKR			
ASE/Shanghai (ASESH)	Assembly Site Origin (22L)	ASO: ASH			
  					
MADE IN: Malaysia 2DC: 20:		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS			
MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750					

Topside Device marking:

Assembly site code for CRS = W

Assembly site code for AKR = 4

Assembly site code for ASH = A

Product Affected:

LM3401MM/NOPB

LM3401MM/S7002589

LM3401MMX/NOPB

LM3401MMX/S7002590

Reference Qualification Data: Approved 7/01/2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LM3401MMX/NOPB(MSL 1-260c)**Package Construction Details**

Assembly Site:	AP1	Mold Compound:	101325958
# Pins-Designator, Family:	8-DGK, VSSOP	Mount Compound:	101374994
Leadframe (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: Plan **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**High Temp Operating Life	125C (500, 1000 Hrs)	77/0	--	--
**High Temp. Storage Bake	170C (420 Hrs)	77/0	--	--
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 ATM (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Destructive Physical Analysis	Post Temp Cycle (500cyc)	pass	pass	pass

Notes: **Tests received preconditioning sequence: MSL1-260C

Reference Qualification Data: Approved 4/08/2010

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: THS4304DGK (MSL 1-260c)**Package Construction Details**

Assembly Site:	ASESH	Mold Compound:	EN2000515
# Pins-Designator, Family:	8-DGK, VSSOP	Mount Compound:	EY1000063
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: Plan **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**High Temp Operating Life	155C (240 Hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 ATM (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	82/0	82/0	82/0
Destructive Physical Analysis	Post Temp Cycle (500cyc)	pass	pass	pass

Notes: **Tests received preconditioning sequence: MSL1-260C

Reference Qualification Data: Approved 4/08/2010

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: TLV2545IDGK (MSL 1-260c)

Package Construction Details

Assembly Site:	ASESH	Mold Compound:	EN2000515
# Pins-Designator, Family:	8-DGK, VSSOP	Mount Compound:	EY1000063
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: Plan **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**High Temp Operating Life	155C (240 Hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	150C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 ATM (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Destructive Physical Analysis	Post Temp Cycle (500cyc)	pass	pass	pass

Notes: **Tests received preconditioning sequence: MSL1-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com